ACKNOWLEDGEMENT RECEIPT

Electronic Version 1.1

Stylesheet Version v1.1.1

Title of Invention

EFS ID:

Elimination of RDL Using Tape Base Flip Chip on Flex for Die Stacking

Submision Type: Information Disclosure

Statement

Application Number:

10/050507

Server Response:

100582 Confirmation

Confirmation Code	Message
ISVR1	Submission was successfully submitted - Even if Informational or Warning Messages appear below, please do not resubmit this application
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First Named Applicant: Teck Lee Attorney Docket Number: MTI-31607

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File Listing:

Doc. Name	File Name	Size (Bytes)	Date
			Produced
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us-ids	MTI-31607c-usidst.xml	1490	2006-01-03
us-ids	us-ids.dtd	7763	2006-01-03
us-ids	us-ids.xsl	12026	2006-01-03
	MTI-31607c-pkda.xml	1732	2006-01-03
package-data	package-data.dtd	27025	2006-01-03
package-data	us-package-data.xsl	19263	2006-01-03
Total files size		69299	

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